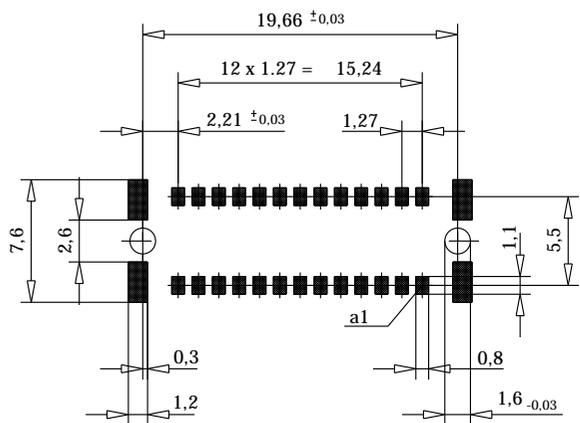
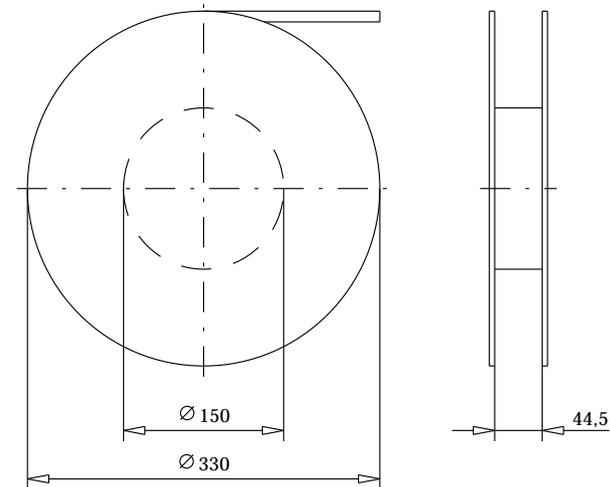


Leiterplatten-Layout Vorschlag für SMT  
PCB-Layout Proposal for SMT

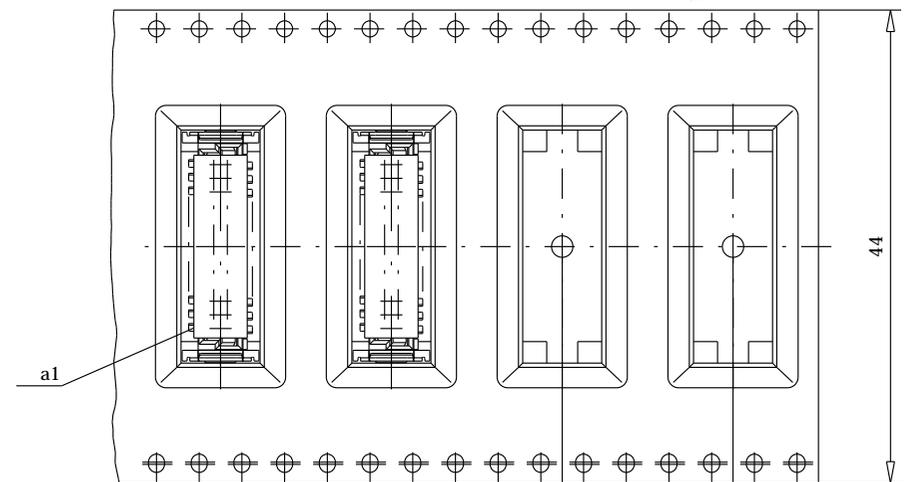


- Anforderungsstufe 1  
Performance Level 1
- Kontaktbereich vergoldet  
Mating Area gold plating
- Anschlussbereich verzinkt 4-6 µm  
Terminal Area 4-6 µm tin plating
- Koplanarität der Anschlüsse ≤ 0.1mm  
Coplanarity Area of Termination ≤ 0.1 mm

Verpackt in Gurtverpackung - Tape on Reel Packaging  
Verpackungseinheit: 280 Stück - Packaging unit: 280 pcs



Abspulrichtung - Reel off Direction



BA7-13 - 8 mm Bauhöhe  
type7-13 - Low Profile

Information:		Tolerances	Scale 3:1
All rights reserved. Only for information. To insure that this is the latest version of this drawing, please contact one of the ERNI companies before using.		 All Dimensions in mm	XXXXX Angaben zu entsprechender Klient-Nr. siehe Fertigungsunterlagen For further information about I.D. number see manufacturing document.
Subject to modification without prior notice. Drawing will not be updated.		Designation	
www.ERNI.com		<b>Messerl. SMC-Q 26-SMD-BA7-13</b> <b>Male SMC-Q 26-SMD-type7-13</b>	
a	11.08.2006	154819	
Index	Date	V:00058689.SZA	SMC

Consider protection memo from DIN 34